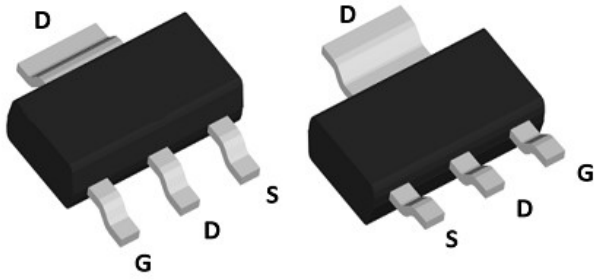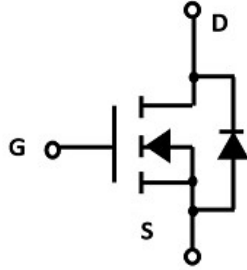# N-Channel Enhancement Mode Field Effect Transistor

SOT-223

Product Summary

- V_{DS} 60V
- I_D 5.0A
- $R_{DS(ON)}$ (at V_{GS}=10V)   ＜100 mohm
- $R_{DS(ON)}$ (at V_{GS}=4.5V)   ＜120 mohm

General Description

- Trench Power MV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

- DC-DC Converters
- Power management functions

■ Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	60	V
Gate-source Voltage	V_{GS}	±20	V
Drain Current	I_D	5.0	A
Pulsed Drain Current [A]	I_{DM}	12	A
Total Power Dissipation @ T_C=25℃	P_D	1.2	W
Thermal Resistance Junction-to-Ambient [B]	$R_{\theta JA}$	105	℃/ W
Junction and Storage Temperature Range	T_J , T_{STG}	-55～+150	℃

■ Electrical Characteristics (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}= 0V, I_D=250μA	60			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V,V_{GS}=0V			1	μA
Gate-Body Leakage Current	I_{GSS1}	V_{GS}= ±20V, V_{DS}=0V			±100	nA
	I_{GSS2}	V_{GS}= ±10V, V_{DS}=0V			±50	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS}, I_D=250μA	1.0	1.7	2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}= 10V, I_D=3A		65	100	mΩ
		V_{GS}= 4.5V, I_D=1.5A		78	120	
Diode Forward Voltage	V_{SD}	I_S=3.0A,V_{GS}=0V		0.8	1.2	V
Maximum Body-Diode Continuous Current	I_S				3.0	A
Dynamic Parameters						
Input Capacitance	C_{iss}	V_{DS}=30V,V_{GS}=0V,f=1MHZ		330		pF
Output Capacitance	C_{oss}			90		
Reverse Transfer Capacitance	C_{rss}			17		
Switching Parameters						
Total Gate Charge	Q_g	V_{GS}=10V,V_{DS}=30V,I_D=3.0A		5.1		nC
Gate-Source Charge	Q_{gs}			1.3		
Gate-Drain Charge	Q_{gd}			1.7		
Turn-on Delay Time	$t_{D(on)}$	V_{GS}=10V,V_{DD}=30V, I_D=1.5A,R_L=1Ω R_{GEN}=3Ω		13		ns
Turn-on Rise Time	t_r			51		
Turn-off Delay Time	$t_{D(off)}$			19		
Turn-off fall Time	t_f			12		

A.　Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.
B.　Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

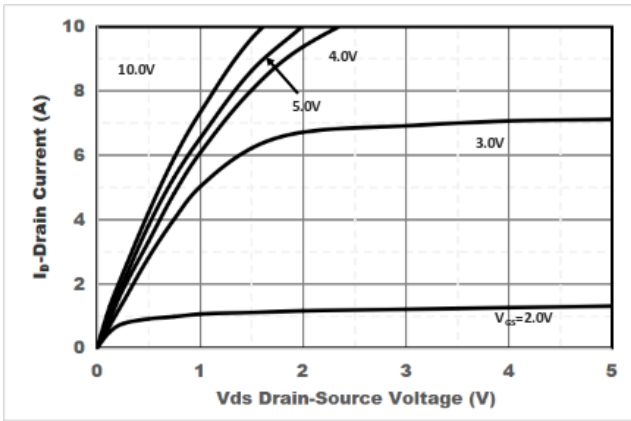■ **Typical Performance Characteristics**
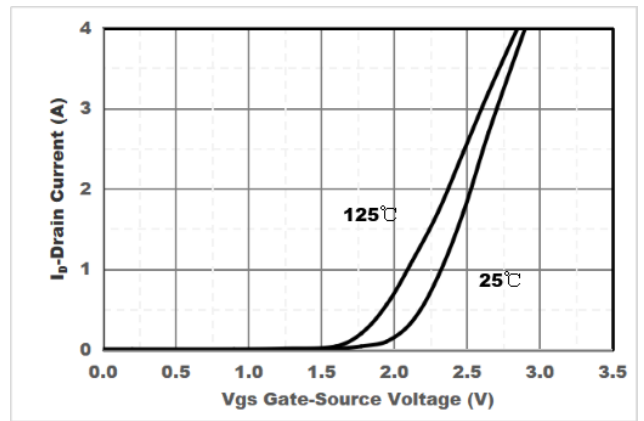

Figure1. Output Characteristics

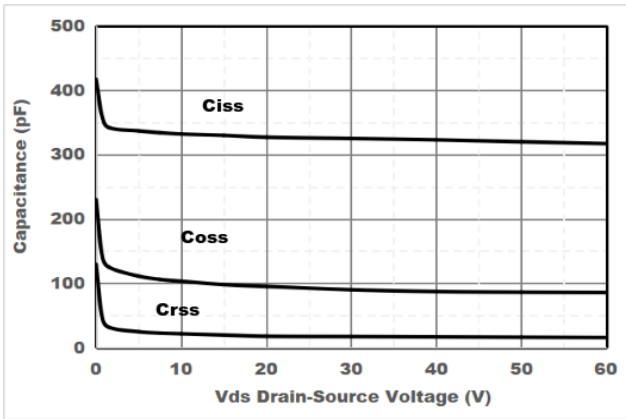Figure2. Transfer Characteristics

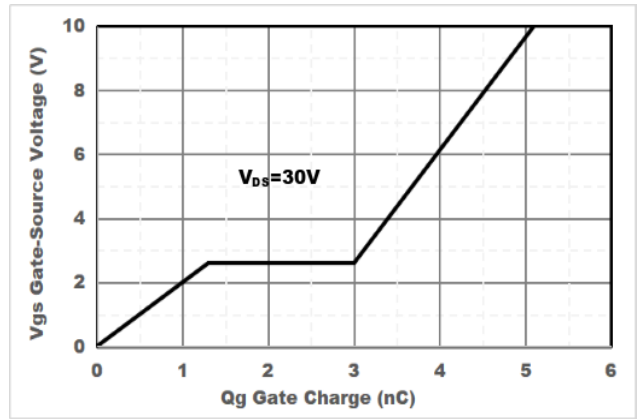Figure3. Capacitance Characteristics
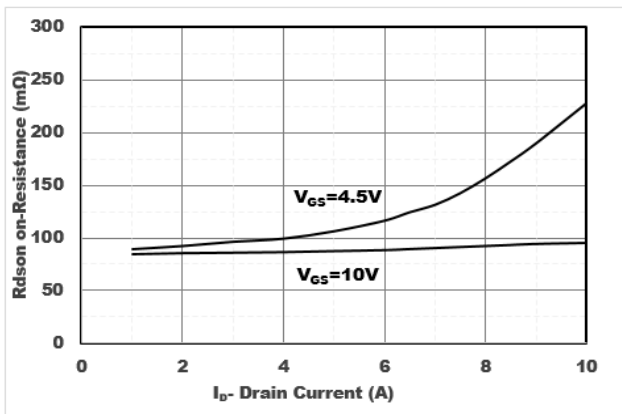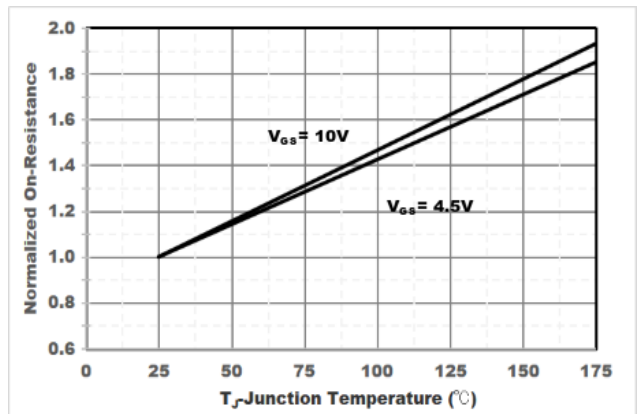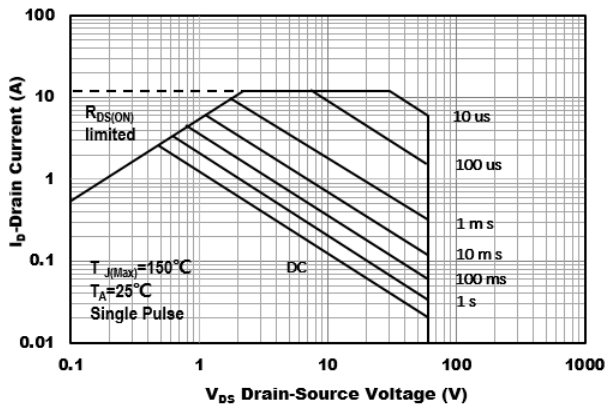

Figure4. Gate Charge

Figure5. Drain-Source on Resistance

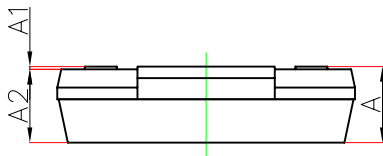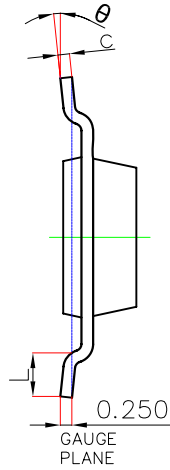Figure6. Drain-Source on Resistance
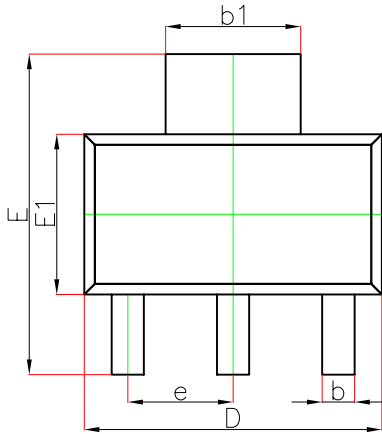
Figure7. Safe Operation Area
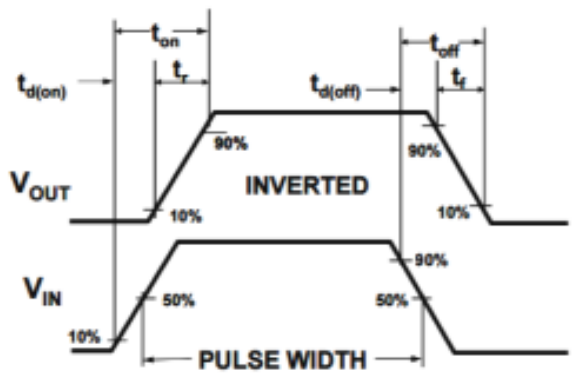
Figure8. Switching wave

■ SOT-223 Package information

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	——	1.800	——	0.071
A1	0.020	0.100	0.001	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.840	0.026	0.033
b1	2.900	3.100	0.114	0.122
c	0.230	0.350	0.009	0.014
D	6.300	6.700	0.248	0.264
E	6.700	7.300	0.264	0.287
E1	3.300	3.700	0.130	0.146
e	2.300(BSC)		0.091(BSC)	
L	0.750	——	0.030	——
θ	0°	10°	0°	10°

■ SOT-223 Suggested Pad Layout
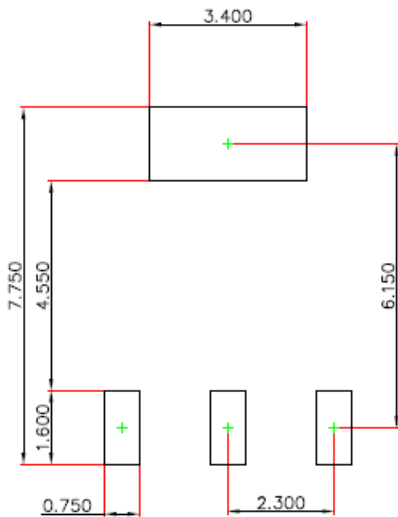
Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.050mm.

3.The pad layout is for reference purposes only.